



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Docket No. TIJ-23462

Yoshida

Serial No. 08/929,263

Art Unit: 1762

Filed: 09/11/97

Examiner: J. Bell

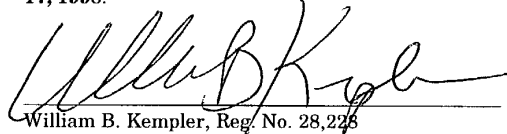
Title: MULTI STEP COAT

AMENDMENT UNDER 37 CFR 1.115

September 17, 1998

Assistant Commissioner for Patents  
Attn.: Box Non-fee Amendments  
Washington, D. C. 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A) I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Box Attn.: Box Non-fee Amendments, Washington, D.C. 20231 on September 17, 1998.

  
William B. Kempler, Reg. No. 28,228

Sir:

In response to the Office Action dated June 17, 1998, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action.

IN THE SPECIFICATION:

Page 2, lines 20 through Page 4, line 9, replace "invention of Claim 1 provides of the semiconductor substrate more reliably" and substitute therefor - provides a method of depositing a resist material on a semiconductor wafer comprising the steps of placing a resist material at a central portion of said semiconductor wafer; spinning said wafer at a first speed for a first predetermined time; spinning said wafer at a second speed which is less than said first speed for a second predetermined time; and spinning said wafer at a third speed, said third speed